

Listing of the Claims:

Kindly replace the previous claim set with the claim set which appears below.

1. (Previously Presented) A lead free soldering material consisting essentially of Sn (tin), 10 wt.% or less Ag (silver), 10 wt.% or less Bi (bismuth), 1 to 3 wt.% Sb (antimony), 0.5 to 3 wt.% Cu (copper), and 1.0 wt.% or less Ni (nickel).
2. (Cancelled)
3. (Previously Presented) A lead free soldering material consisting essentially of Sn (tin), 2 to 10 wt.% Ag, Bi, 1 to 3 wt.% Sb, 0.5 to 3 wt.% Cu and 0.05 to 0.3 wt.% Ni, wherein the Sb:Bi wt.% ratio is from 1:1.5-3.
- 4-6. (Cancelled)
7. (Previously Presented) Soldering material according to Claim 1 wherein there exists a ratio Sb:Bi of 1:1.5 to 3, based on the weight of Sb and Bi.
8. (Previously Presented) Soldering material according to Claim 7 having a Ni content of 0.05 to 0.2 wt.%.
9. (Previously Presented) Soldering material according to Claim 1 wherein the soldering material is SnAg3.3-4.7Cu0.3-1.7Bi2Sb1Ni0.2.
- 10-14. (Cancelled)

15. (Previously Presented) Soldering material according to Claim 3 wherein there exists a ratio Sb:Bi of 1:1.5 to 3, based on the weight of Sb and Bi.

16-18. (Cancelled)

19. (Previously Presented) A solder joint formed from the lead free soldering material of Claim 1.

20-25. (Cancelled)

26. (Previously Presented) A lead free soldering material consisting essentially of Sn (tin), 2 to 10 wt.% Ag, 1 to 3 wt.% Bi, 1 to 3 wt.% Sb, 0.5 to 3 wt.% Cu and 0.05 to 0.3 wt.% Ni.